This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. **(Currently Amended)** ~~Electroplatingplating~~ An electroplating solution for copper comprising $CuSO_4 \cdot 5H_2O$, H_2SO_4, HCl, ~~Polyethylenglycol (molecular weight >200)~~ polyethylene glycol with a molecular weight greater than 200, hydroxyl amine sulfate, and hydroxyl amine chloride ~~and if necessary further additives~~.

2. **(Currently Amended)** ~~Solution~~ A solution according to claim 1 further comprising ~~Cl~~ Cl^- ions in a range of 50 – 150 ppm and the hydroxyl amine sulfate in a range of ~~0,01~~ 0.01 – 5 g/l.

3. **(Currently Amended)** ~~Solution~~ A solution according to claim 1 further comprising ~~Cl~~ Cl^- ions derived at least from HCl in a range of 55 – 125 ppm.

4. **(New)** An electroplating solution according to claim 1, further comprising an additive.

5. **(New)** A solution according to claim 4, wherein the additive is thiourea, molasses, glucose, tribenzylamine, benzotriazole, naphthalene sulfonic acid, or $(NH_2OH)_2 \cdot H_2SO_4$.

6. **(New)** An electroplating solution made by comprising:

$CuSO_4 \cdot 5H_2O$;

H_2SO_4;

HCl, and

optionally an additive; and

polyethylene glycol with a molecular weight greater than 200, and either hydroxyl amine sulfate or hydroxyl amine chloride.

7. **(New)** An electroplating solution comprising:

$CuSO_4 \cdot 5H_2O$;

H_2SO_4;

Cl^- ions, and

polyethylene glycol with a molecular weight greater than 200.

8. **(New)** An electroplating solution according to claim 7, wherein the concentration of $CuSO_4 \cdot 5H_20$ is 60 – 150 g/l, H_2SO_4 is 80 – 150 g/l, ~~Cl~~ Cl^- ions are 50 – 150 ppm, polyethylene glycol is less than 100 ppm, and optionally an additive.

9. **(New)** An electroplating solution according to claim 7, further comprising hydroxyl amine sulfate or hydroxyl amine chloride.